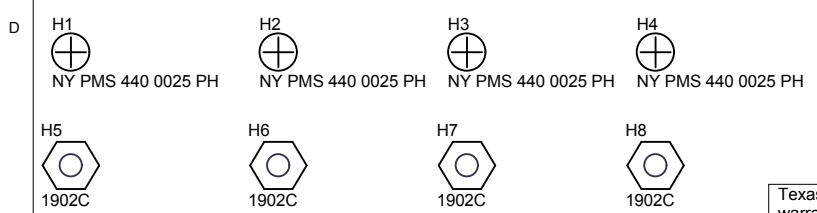


TEXT TO BE PLACED IN SILK SCREEN ON PCB

- 10% APD
- 5% APD
- 20% APD

TEXT TO BE PLACED IN SILK SCREEN ON PCB

TEXT TO BE PLACED IN SILK SCREEN ON PCB



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 11/23/2015
TID #: TIDA-00725	Project Title: Transimpedance Amplifier_OPA857_THS4541	
Number: 6590370	Rev: A	Sheet Title: *
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: * of *
Drawn By: *	File: TIA_OPA857_THS4541-A.SchDoc	Size: B
Engineer: Samir Cheria	Contact: http://www.ti.com/support	

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